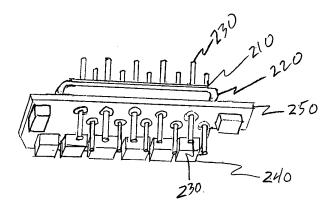
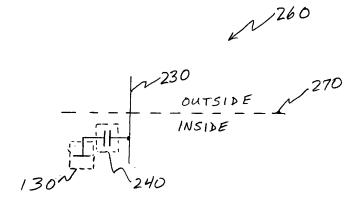


200

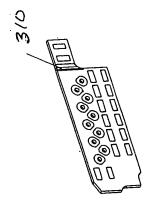


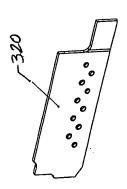
F16.2A



F16. 2B

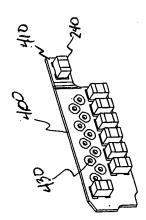
300

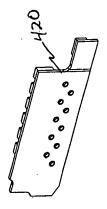


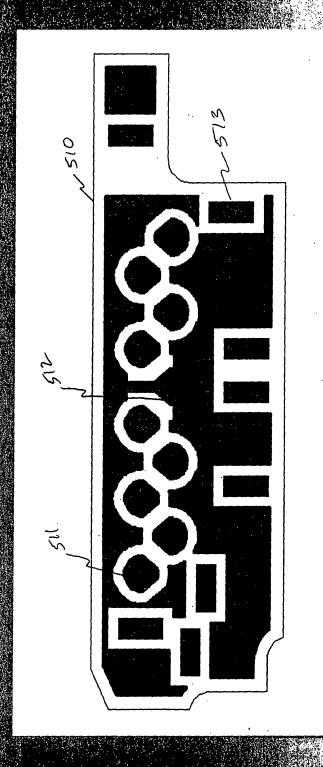


F16.3





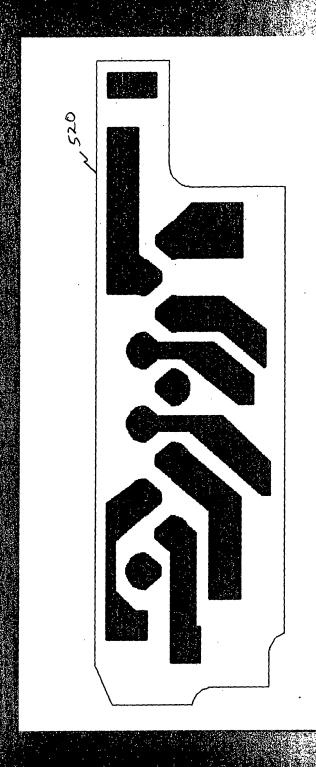




F16.5A

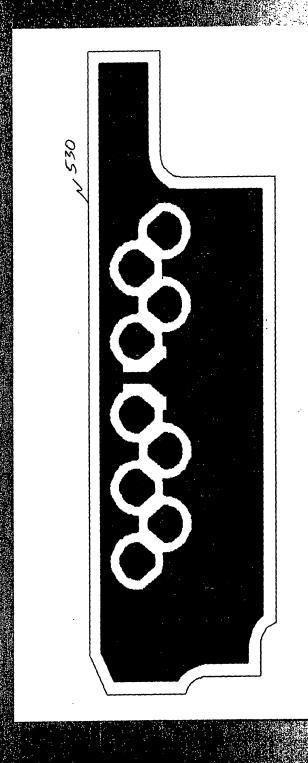
1





F16.58

## Ground - Layer 3



F16 5C

FORMING A HERMETIC SEAL AROUND
A PLURALITY OF I/O PINS THAT
PASS THROUGH A HERMETIC SEAL

FORMING EMI FILTER CIRCUITS
USING DISCRETE CAPACITORS
HOUNTED ON A PRINTED CIRCUIT
SUBSTRATE

Attacking the I/O conductors to
the printed circuit substrate and
the EMI filter circuits

F16.6